


MATERIAL DECLARATION SHEET



Package Type	CDSOT23 (CDSOT23-TxxLC)					
Product Line	Semiconductor Products					
Compliance Date	Aug 19, 2022					
RoHS Compliant	Yes	Terminal	e3	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.00558906	Amorphous Silica	60676-86-0	87.600	50.87945488	54.655364
				Epoxy Resin A	Proprietary	4.900	1.40530447	
				Epoxy Resin B	29690-82-2	4.000	1.26570316	
				Phenol Resin	Proprietary	3.000	0.86039049	
				Carbon Black	1333-86-4	0.500	0.24451084	
2	Leadframe	Copper Alloy	0.00394239	Copper	7440-50-8	97.100	37.51954175	38.552571
				Iron	7439-89-6	2.289	0.77759612	
				Phosphorus	7723-14-0	0.020	0.00157429	
				Zinc	7440-66-6	0.100	0.03071156	
				Lead	7439-92-1	0.010	0.00487772	
3	Chip	Silicon	0.00033403	Silver	7440-22-4	0.481	0.21826914	3.266437
				Silicon	7440-21-3	88.374	2.89823731	
				Nickel	7440-02-0	5.913	0.19394867	
				Aluminum	7429-90-5	5.347	0.16224558	
				Gold	7440-57-5	0.366	0.01200593	
4	Die Attach	Silver Epoxy	0.00009696	Silver	7440-22-4	75.000	0.85105170	0.948159
				Epoxy resin	9003-36-5	19.900	0.08483571	
				1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	3.000	0.00356971	
				Aromatic polyamine	Proprietary	2.000	0.00855476	
				Adipic acid	124-04-9	0.100	0.00014712	
5	Bond Wires	Copper	0.00002508	Copper	7440-50-8	98.700	0.24095649	0.245222
				Non - Cu element	Proprietary	1.300	0.00426600	
6	Lead Finish	Matte Tin	0.00023848	Tin	7440-31-5	100.000	2.33224660	2.332247
		Total Weight	0.0102260					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.